

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	885	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) and ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:09
L2	748	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) and ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film)) and (interconnect or interconnection)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:09
L3	733	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) and ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film)) and (interconnect or interconnection) and (insulating or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:09
L4	555	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) and ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film)) and ((interconnect or interconnection) near10 (insulating or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:10
L5	184	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) and ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film)) same ((interconnect or interconnection) near10 (insulating or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:10
L6	37	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) same ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film))) same ((interconnect or interconnection) near10 (insulating or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:10

L7	20	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) same ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film))) same ((interconnect or interconnection) near10 (insulating or dielectric)) same trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:12
L8	1	((diffusion or diffuse or diffusing or diffused) near5 barrier near5 (film or layer) near5 (copper or cu)) same ((etch or etching) near5 (stop or stopping or barrier) near5 (layer or film))) same ((interconnect or interconnection) near10 (insulating or dielectric)) same trench).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:12
L9	1	09/883370	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:13
L10	0	11 and 09/883370	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:13
L11	113	(interconnect or interconnection) with substrate with trench with (barrier) with (copper or cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:13
L12	64	(interconnect or interconnection) with (insulation or insulating or dielectric) with substrate with trench with (barrier) with (copper or cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:14
L13	25	((interconnect or interconnection) with (insulation or insulating or dielectric) with substrate with trench with (barrier) with (copper or cu)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:14
L14	355	((first or lower or bottom) near2 (diffusion or diffusing or diffuse) near2 barrier near2 (film or layer)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:15

L15	152	((first or lower or bottom) near2 (diffusion or diffusing or diffuse) near2 barrier near2 (film or layer)).ti,ab,clm. same ((second or upper or top) near2 (diffusion or diffusing or diffuse) near2 barrier near2 (film or layer)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:16
L16	17	((first or lower or bottom) near2 (diffusion or diffusing or diffuse) near2 barrier near2 (film or layer)).ti,ab,clm. same ((second or upper or top) near2 (diffusion or diffusing or diffuse) near2 barrier near2 (film or layer)).ti,ab,clm. and (barrier near5 (copper or cu)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:20
L17	20	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer)).ti, ab,clm. same ((second or upper or top) near2 (diffusion or diffusing or diffuse) near2 barrier near2 (film or layer)).ti,ab,clm. and (barrier near5 (copper or cu)).ti, ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:21
L18	916	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:21
L19	92	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:23
L20	16	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) with ((second or upper or top) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:24

L21	39	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and ((second or upper or top) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:24
L22	37	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and ((second or upper or top) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and (etch or etching)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:24
L23	8	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and ((second or upper or top) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and ((etch or etching) near (stop or stopping or barrier))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:26
L24	4	((first or lower or bottom) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and ((second or upper or top) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventive or preventing or barrier) near2 (film or layer) near2 (copper or cu)) and ((diffusion or diffusive or diffuse or diffusing) near5 ((etch or etching) near (stop or stopping or barrier)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:27

L37	47	I36 and ((etch or etching) near (stop or stopping or barrier) near (layer or film))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:35
L38	54	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:35
L39	44	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)) and ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:35
L40	43	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)) and ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventing or prevention or preventive or barrier or prevented))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:36
L41	13	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)) and ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventing or prevention or preventive or barrier or prevented)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:36
L42	9	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)).ti,ab,clm. and ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventing or prevention or preventive or barrier or prevented)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:38
L43	13	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)) and ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventing or prevention or preventive or barrier or prevented)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:38

L44	5	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)) and ((first or second or upper or lower or top or bottom) near ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventing or prevention or preventive or barrier or prevented))))).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:38
L45	6	I36 and ((etch or etching) near2 (stop or stopping or barrier) near2 (layer or film)) and ((first or second or upper or lower or top or bottom) near2 ((copper or cu) near2 (diffusion or diffusive or diffusing or diffuse) near2 (prevent or preventing or prevention or preventive or barrier or prevented))))).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/25 14:38